

**TOREX SEMICONDUCTOR LTD.**  
Quality Assurance Dept.

## Composition Table

Product(Pb-free): XCM524xxxxDR-G  
Typical Mass: 9 mg

Part name	Weight(mg)	Material name	Ratio(ppm)	CAS number
Silicon chip	1.272	Silicon	141400	7440-21-3
	-	Arsenic	8	7440-38-2
Lead pad	2.248	Nickel	249800	7440-02-0
	0.178	Silver	19800	7440-22-4
	0.033	Gold	3600	7440-57-5
Die attach	0.025	Epoxy Resin	2800	—
	0.022	Silica	2500	60676-86-0
Bonding wire	0.255	Gold	28300	7440-57-5
Resin	4.470	Silica	496700	60676-86-0
	0.273	Epoxy Resin	30400	—
	0.224	Phenol Resin	24800	—

\* The component composition is based on the information provided by raw material vender.

\* The mass of the IC and its fractions could be different due to the manufacturing conditions of materials.

\* Any indication "-" in CAS number means "confidential."